

# SOT1906-2

WLCSP214, wafer level chip-scale package, 214 terminals,  
0.5 mm pitch, 9.418 mm x 7.918 mm x 0.55 mm body

12 April 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP214
<b>Package type industry code</b>	WLCSP214
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	28-3-2018
<b>Manufacturer package code</b>	98ASA01053D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	7.918	-	mm
E	package width	-	-	9.418	-	mm
A	seated height	-	-	0.55	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	214	-	A/A



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## 2. Package outline

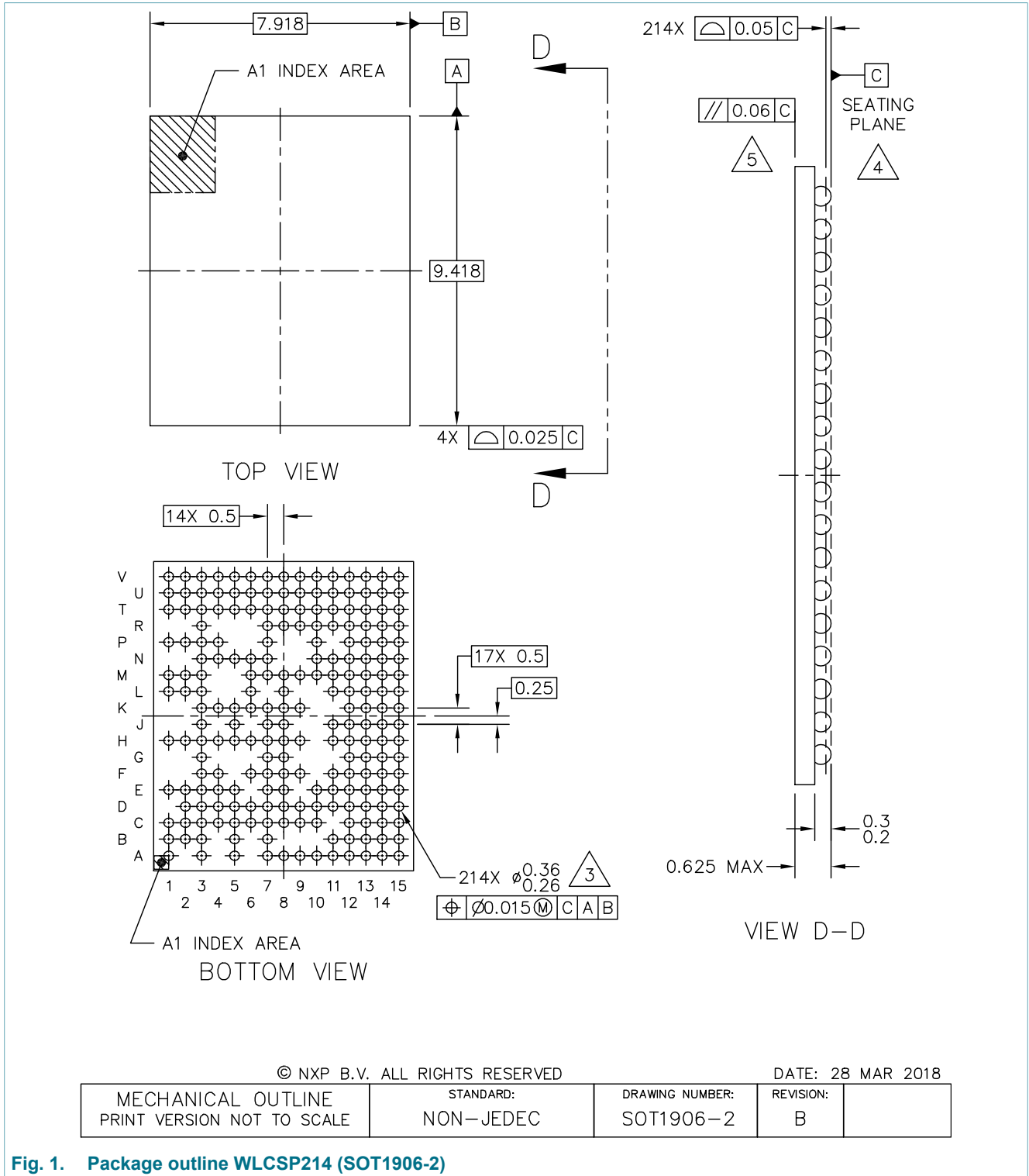


Fig. 1. Package outline WLCSP214 (SOT1906-2)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 28 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: SOT1906-2	REVISION: B	
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Fig. 2. Package outline note WLCSP214 (SOT1906-2)

### 3. Legal information

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